

# Whisker and JISSO Material Study Group

## ◆ Scope

- Enactment and revision of IEC and JIS standards and case studies of test methods related to whisker generation.
- Utilizing the organizational characteristics of the study group, we will investigate future JISSO, parts, and materials, and propose JISSO issues and the direction to be set next.

## ◆ Activity

- In response to a request from the Ministry of Economy, Trade and Industry of Japan in 2001, the IEC standard IEC 60068-2-82 "Environmental testing --Part 2-82: Tests --Test" was established by "Standardization of joint reliability in high-density mounting". We have been the first in the world to tackle issues related to whiskers, such as the establishment of "XW1: Whisker test methods for electronic and electric components" and JEITA ET-7305 "Guidelines for selecting lead-free materials that suppress tin whiskers."
- This activity is a unique activity that brings together more than 27 organizations of domestic electronic component assembling, electronic components, solder or plating metal materials, processing manufacturers and research institutes. Therefore, against this background, we changed the name to "Whisker and JISSO Material Study Group" to "think about problems related to materials that will be the basis of future JISSO" from various perspectives as well as whiskers.

## ◆ Standard system & Documents

IEC standards	JIS standards	JEIATA standards	Document title
IEC 60068-2-82 (Revised in May 2019)	JIS C 60068-2-82 (Established in 2009) (Revised in Feb. 2021)	---	Whisker test methods for electronic and electric components
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		ET-7035	Interim report of survey and evaluation of Sn whisker growth on low-temperature soldering